



# Improvement of heat transfer analytical models for thermoplastic injection molding and comparison with experiments



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## ABSTRACT

The aim of analytical models presented in this paper was to provide a first set of data for choosing thermal conditions during thermoplastic injection molding. Two different models allowed the quick determination of the cooling/solidifying time, the mold surface temperature variation and the heat flux densities exchanged between the polymer and the mold. The first model specific to amorphous polymers was based on the 1D heat conduction equation. The second model dedicated to semi-crystalline polymer was based on the adaptation of the solution of the Stefan problem for part with a finite thickness. For each case, the influence of the thermal contact resistance between polymer and the mold on the cooling/solidifying time was highlighted. Then, the description of heat transfer in the mold allowed to determine the time needed to produce reliable parts when the mold was in periodic steady state. The attenuation of the periodic temperature variation through the thickness of the mold was evaluated through the penetration depth. Parameters calculated from these analytical models were compared with experimental results obtained with an instrumented mold or with data computed with a coupled model. The good agreement between them validated the interest to these models to get quickly reliable characteristic parameters of injection molding.

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## 1. Introduction

Injection molding is the most used process in amorphous and semi-crystalline polymers forming. This is a cyclic process, in which each cycle can be decomposed in several steps: The filling step consists in injecting the melted polymer in the molding cavity during a short time. During the packing phase, a pressure is applied to the polymer to compensate the thermal and crystallization shrinkages until the freezing of the gate. The cooling of the part continues until the part is solidified enough to be ejected. The cooling phase being the most significant step of the process cycle in terms of time, its determination is of primary importance to estimate production capabilities and costs. Heat transfer in the process can be described in a first approach by designers' experience and the use of simple formulas [1] even for the design of conformal cooling channel [2]. This approach can be completed using simulations such as commercial software, especially for complex geometry parts. However, their use may be time-consuming in terms of computation and also requires input data especially boundary conditions and material properties, which are sometimes difficult to

obtain. In this context, different analytical models have been developed to provide quickly a first set of data for mold designers.

Simplified modeling [3,4] used for cooling time calculation is based on the heat conduction equation. Indeed, natural convection does not occur due to the very high viscosity of melted polymer (more than 1000 Pa·s). Moreover, even during the filling (less than 5% of the cooling time), the thermal shock of the melted polymer on the mold induces a high conductive heat flux (more than  $3 \cdot 10^5 \text{ W/m}^2$ ) which is several orders of magnitude higher than the convective heat flux [5]. The assumptions of these models include the use of average thermophysical properties as well the boundary conditions that are assumed constant and uniform.

Nevertheless, these methods cannot be used for semi-crystalline polymers since they do not consider the crystallization. Indeed, heat transfer and crystallization are strongly coupled: the crystallization depends on the temperature, pressure and mechanical stresses, while the temperature field is influenced by the crystallization enthalpy released and by the dependence of thermophysical properties according to the crystallinity and temperature. The coupling can be simplified if the Deborah  $D_e$  number is low (Eq. (1)), what means that the solidification half-time  $t_{solid}/2$  is small compared to the characteristic conduction time  $e^2/a_p$ , as proposed by Bénard and Advani [6] (Eq. (1)). In this case, the phase

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